



# TECHNICAL SPECIFICATION



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**Nanomanufacturing – Key control characteristics –  
Part 6-9: Graphene-based material – Sheet resistance: Eddy current method**

INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

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## CONTENTS

FOREWORD.....	4
INTRODUCTION.....	6
1 Scope.....	7
2 Normative references .....	7
3 Terms and definitions .....	7
3.1 General terms .....	8
3.2 Terms related to the measurement method .....	8
3.3 Key control characteristics .....	9
4 Abbreviated terms .....	10
5 General .....	10
5.1 Measurement principle .....	10
5.2 Measurement configuration .....	10
5.3 Measurement mode .....	11
5.3.1 Single point mode .....	11
5.3.2 Imaging scanning mode .....	11
5.4 Measurement system .....	11
5.4.1 Measurement equipment .....	11
5.4.2 Calibration standards.....	12
5.4.3 Ambient conditions .....	12
5.4.4 Sample preparation method.....	13
6 Measurement procedure .....	13
6.1 Calibration of test equipment .....	13
6.2 Verifying calibration .....	14
6.3 Description of the measurement procedure .....	14
7 Data analysis / interpretation of results .....	14
7.1 Single point sheet resistance measurement .....	14
7.2 Sheet resistance imaging.....	15
7.2.1 General .....	15
7.2.2 Line profile analysis.....	15
7.2.3 Histogram analysis .....	15
7.2.4 Statistical analysis.....	15
7.3 Individual homogeneity assessment.....	15
7.4 Defect identification .....	15
8 Test report.....	16
8.1 General.....	16
8.2 Sample identification.....	16
8.3 Test conditions .....	16
8.4 Measurement specific information.....	16
8.5 Test results.....	16
Annex A (informative) Worked example and test report.....	17
A.1 General.....	17
A.2 Sample identification.....	17
A.3 Geometry of the sample and scanning method.....	18
A.4 Measurement related information.....	18
Annex B (informative) Comparison between eddy current and four point probe measurement.....	20

B.1	General.....	20
B.2	Results .....	20
Annex C (informative)	Use case quality inspection.....	22
C.1	General.....	22
C.2	Analysis of the sheet resistance distribution for quality inspection.....	22
C.3	Analysis example .....	22
Annex D (informative)	Reference sample sets.....	25
Bibliography	.....	26
Figure 1	– Scheme of measurement setup .....	12
Figure A.1	– Sheet resistance map with histogram.....	19
Figure B.1	– Correlation of the results of sheet resistance measured by the eddy current (EC) method and by the four point probe (4PP) method .....	21
Figure C.1	– Sheet resistance image of 200 mm × 200 mm graphene sheet.....	22
Figure C.2	– Line profile analysis .....	23
Figure C.3	– Histogram view of the whole sample .....	23
Figure C.4	– Histogram analysis (high sheet resistance area).....	23
Figure C.5	– Histogram analysis (good area) .....	24
Figure C.6	– Selective area analysis (used specified shape).....	24
Figure C.7	– Selective area analysis (regular shape) .....	24
Figure D.1	– Sheet resistance reference sample set 300 mm × 300 mm .....	25
Table A.1	– Product identification .....	17
Table A.2	– General material description .....	17
Table A.3	– Geometry of the sample and scanning parameter.....	18
Table A.4	– Measurement related information .....	18
Table A.5	– Test results: Sheet resistance .....	18
Table B.1	– Comparison of the results of sheet resistance measured by the eddy current method and by the four point probe method .....	20
Table B.2	– Measurement accuracy .....	21

## INTERNATIONAL ELECTROTECHNICAL COMMISSION

**NANOMANUFACTURING – KEY CONTROL CHARACTERISTICS –****Part 6-9: Graphene-based material – Sheet resistance:  
Eddy current method**

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The language used for the development of this Technical Specification is English.

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## INTRODUCTION

The application of graphene and graphene-related materials as a conductive large-area electrode material has become of rising interest during recent years. Especially in the application of graphene as a replacement material for indium tin oxide (ITO), graphene combines low sheet resistance and high optical transparency. In particular, the application of optically transparent large-area graphene layers has become more important. Hence, the electrical characterization of large-area graphene layers is essential.

However, contacting methods, such as four-probe measurements, can cause damage to the graphene and deteriorate its quality.

Non-contact methods have advantages for measurement of the sheet resistance since damage to the layers is avoided and it is possible to readily scan the film to examine homogeneity.

The sheet resistance can serve as a measure for the electrical characterization due to its direct dependence on conductivity and graphene quality for electrical applications.

## NANOMANUFACTURING – KEY CONTROL CHARACTERISTICS –

### Part 6-9: Graphene-based material – Sheet resistance: Eddy current method

#### 1 Scope

This part of IEC 62607 establishes a standardized method to determine the key control characteristic

- sheet resistance

for films of graphene-based materials by

- eddy current method.

With this method a coil-generated primary alternating electromagnetic field induces eddy currents in the conducting layer to be measured. The superposition of the primary field with the secondary field induced by the eddy currents is a function of the sheet resistance of the layer.

- The method is applicable for the contactless measurement of the sheet resistance of large area graphene layers on non-conductive substrates. As the method avoids any physical contact, it prevents any mechanical damage to the sensitive graphene layer. Therefore, the method is suitable for electrical characterization and quality control in an industrial fabrication environment.
- Due to the use of two detectors – one above the substrate and one below the substrate – the method is insensitive regarding small deviations from perfect flatness of the substrate.
- The range of graphene layers to be characterized comprises any quality, size and morphology of graphene crystallites. Hence, the applicability of this method spans from high quality, defect-free graphene layers to layers of dried graphene ink.
- The size of the graphene layers to be characterized includes layers larger than 25 mm × 25 mm for single point testing and 50 mm × 50 mm for imaging testing.
- The method can be used for layers of graphene-based material with a sheet resistance in the nominal range of 10 Ω/sq to 5 000 Ω/sq.

#### 2 Normative references

There are no normative references in this document.